

C0402C392J4RACTU

Aliases (C0402C392J4RAC7867) SMD Comm X7R, Ceramic, 3,900 pF, 5%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0402, 0.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.21 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3,900 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	16 VDC
Dielectric Withstanding Voltage	40 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

 Dimensions

 Chip Size
 0402

 L
 1mm +/-0.05mm

 W
 0.5mm +/-0.05mm

 T
 0.5mm +/-0.05mm

 S
 0.3mm MIN

 B
 0.3mm +/-0.1mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	10000

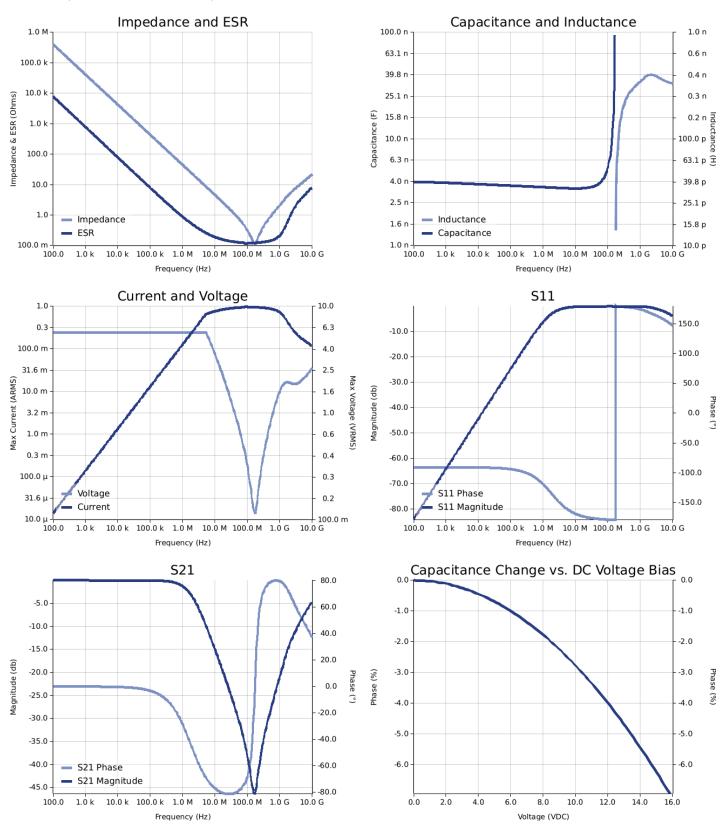
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Simulations

For the complete simulation environment please visit K-SIM.





Temperature (C)

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Voltage (VAC)

Capacitance Change versus Temperature Capacitance Change versus AC Voltage 4.0 4.0 0.0-0.0 3.0 3.0 -2.0 -2.0 2.0 2.0 Capacitance Change (%) Capacitance Change (%) Capacitance Change (%) 1.0 1.0 -4.0 -4.0 0.0 0.0 -1.0 -1.0 -6.0 -6.0 -2.0 -2.0 -3.0 -3.0 -8.0 -8.0 -4.0 -4.0 -5.0 -5.0 -10.0 -10.0 -6.0 -6.0 -60.0 -40.0 -20.0 0.0 20.0 40.0 60.0 80.0 100.0 120.0 140.0 0.5 1.0 1.5 2.0 2.5 3.0 0.0

Capacitance Change (%)



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.